TEXAS INSTRUMENTS
Data sheet acquired from Harris Semiconductor
SCHS107B – Revised July 2003

CD40194B Types

CMOS 4-Bit Bidirectional Universal Shift Register

NOT RECOMMENDED FOR NEW DESIGNS

High-Voltage Types (20 Volt Rating)

■ CD40194B is a universal shift register featuring parallel inputs, parallel outputs SHIFT RIGHT and SHIFT LEFT serial inputs, and a direct overriding clear input. In the parallel-load mode (S0 and S1 are high), data is loaded into the associated flip-flop and appears at the output after the positive transition of the CLOCK input. During loading, serial data flow is inhibited. Shift right and shift left are accomplished synchronously on the positive clock edge with data entered at the SHIFT RIGHT and SHIFT LEFT serial inputs, respectively. Clocking of the register is inhibited when both mode control inputs are low. When low, the RESET input resets all stages and forces all outputs low.

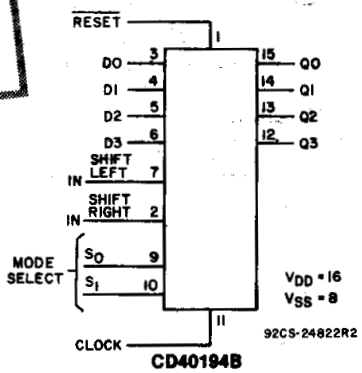
The CD40194B types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Features:

- **Medium-speed: f_{CL} = 12 MHz (typ.) @ V_{DD} = 10 V**
- **Fully static operation**
- **Synchronous parallel or serial operation**
- **Asynchronous master reset**
- **Standardized, symmetrical output characteristics**
- **5-V, 10-V, and 15-V parametric ratings**
- **Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"**

Applications:

- **Arithmetic unit bus registers**
- **Serial/parallel conversions**
- **General-purpose register for bus-organized systems**
- **General-purpose registers**



CD40194B
FUNCTIONAL DIAGRAM

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)..... 100mW
OPERATING-TEMPERATURE RANGE (T_A) .....-55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) .....-65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

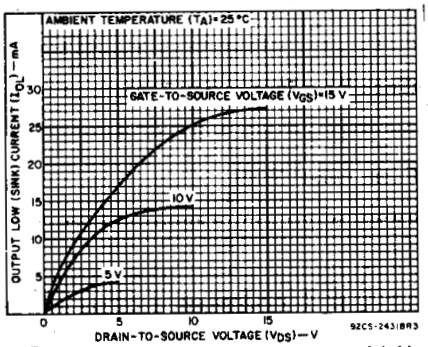


Fig. 1—Typical n-channel output low (sink) current characteristics.

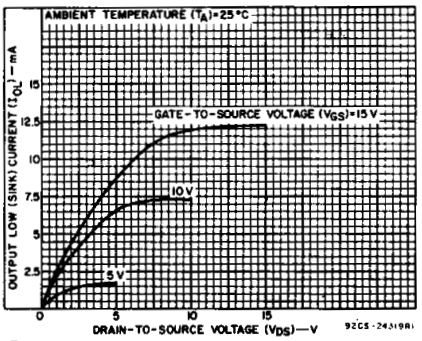


Fig. 2—Minimum n-channel output low (sink) current characteristics.

RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC		VDD (V)	LIMITS Min.	LIMITS Max.	UNITS
Supply-Voltage Range (For Package-Temperature Range)			3	18	V
Setup Time, D0, D3, SR_{IN}, SL_{IN} to clock	t_s	5	100	—	ns
		10	70	—	
		15	50	—	
SELECT 0, SELECT 1 to clock		5	400	—	
		10	220	—	
		15	130	—	
Hold Time, D0, D03, SR_{IN}' SL_{IN} to clock	t_H	5	0	—	
		10	0	—	
		15	0	—	
SELECT 0, SELECT 1 to clock		5	0	—	
		10	0	—	
		15	0	—	
Clock Pulse Width,	t_W	5	180	—	
		10	80	—	
		15	50	—	
Clock Input Frequency	f_{CL}	5	—	3	MHz
		10	—	6	
		15	—	8	
Clock Input Rise or Fall Time,	t_rCL, t_fCL	5	1000	—	μs
		10	100	—	
		15	100	—	
Reset Pulse Width,	t_{WR}	5	300	—	ns
		10	200	—	
		15	140	—	

CONTROL TRUTH TABLE FOR CD40194B SERIES

CLOCK	MODE SELECT S_0	MODE SELECT S_1	$\overline{RESET}$	ACTION
X	0	0	1	No Change
⌐	1	0	1	Shift Right (Q0 toward Q3)
⌐	0	1	1	Shift Left (Q3 toward Q0)
⌐	1	1	1	Parallel Load
X	X	X	0	Reset

1 = High level
0 = Low level
X = Don't care
▲ = Level change

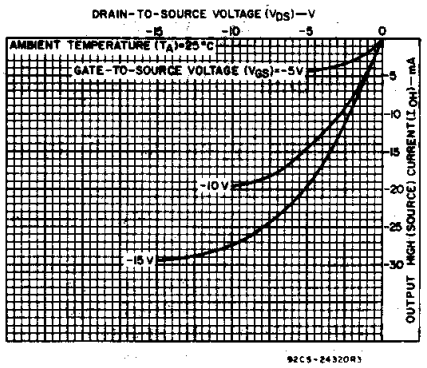


Fig. 3—Typical p-channel output high (source) current characteristics.

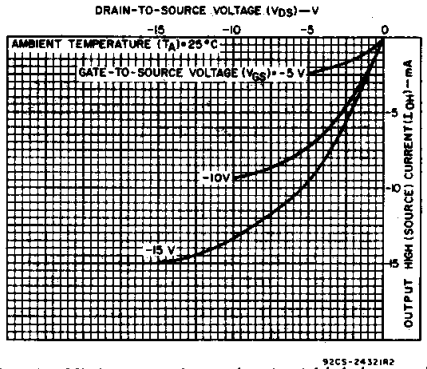


Fig. 4—Minimum p-channel output high (source) current characteristics.

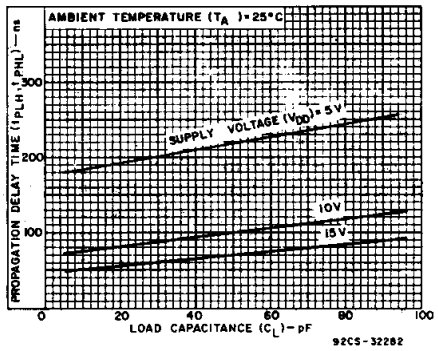


Fig. 5—Typical propagation delay time as a function of load capacitance, (CLOCK to Q).

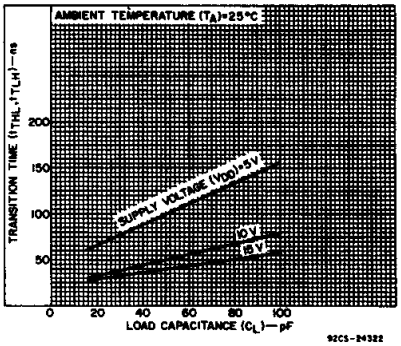


Fig. 6—Typical transition time as a function of load capacitance.

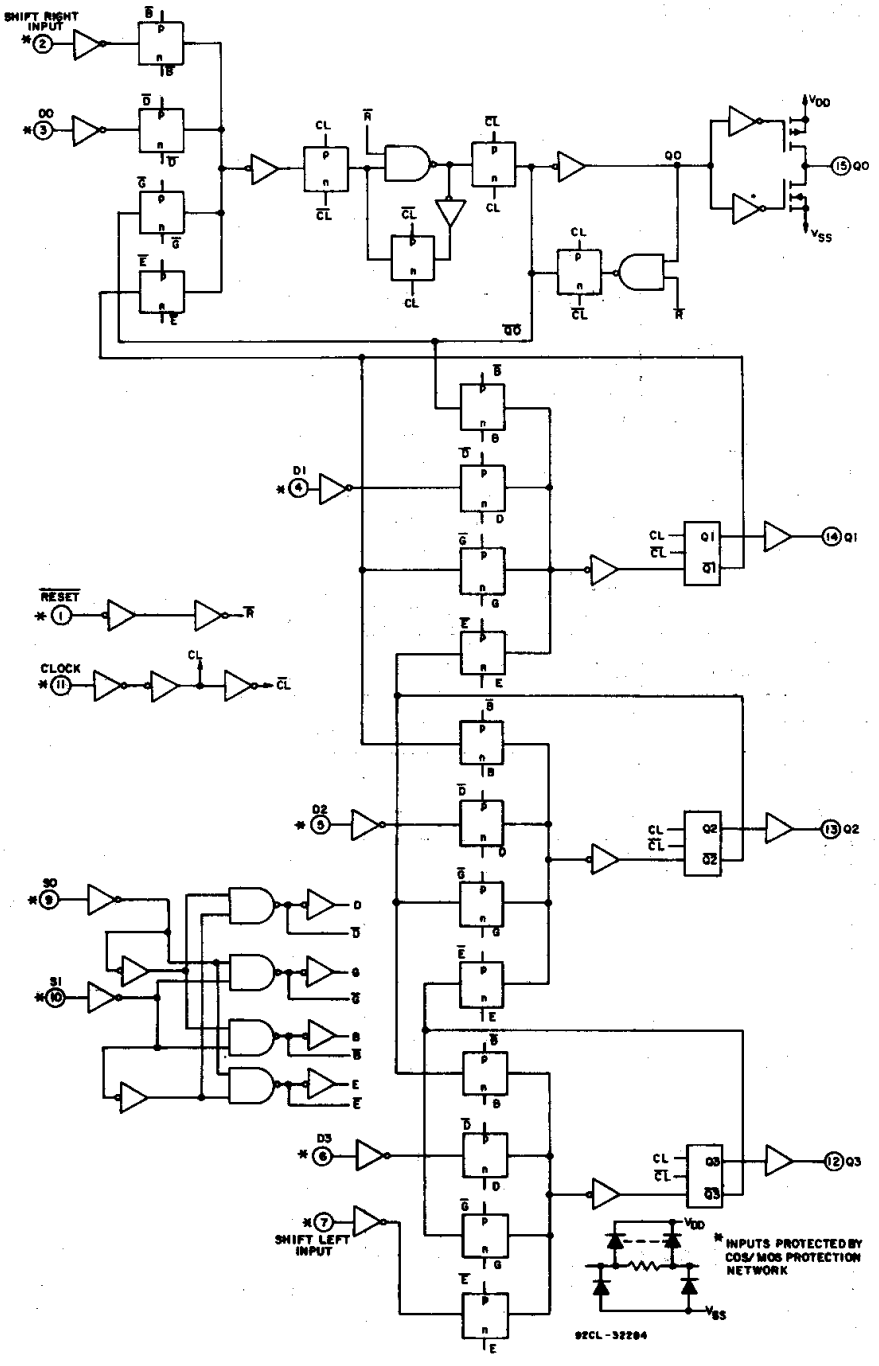


Fig. 8—CD40194B logic diagram.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								+25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current, I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	—	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	—	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	—	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	—	
Output Voltage: Low-Level, V_{OL} Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	—	0,5	5	4.95				4.95	5	—	
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage, V_{IL} Max.	0.5,4.5	—	5	1.5				—	—	1.5	
	1,9	—	10	3				—	—	3	
	1.5,13.5	—	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5,4.5	—	5	3.5				3.5	—	—	
	1,9	—	10	7				7	—	—	
	1.5,13.5	—	15	11				11	—	—	
Input Current I_{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	$\pm 10^{-5}$	±0.1	μA
3-State Output Leakage Current, I_{OUT} Max.	0,18	0,18	18	±0.4	±0.4	±12	±12	—	$\pm 10^{-4}$	±0.4	μA

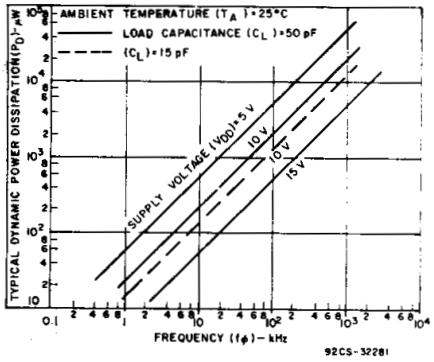


Fig. 9—Typical power dissipation as a function of frequency.

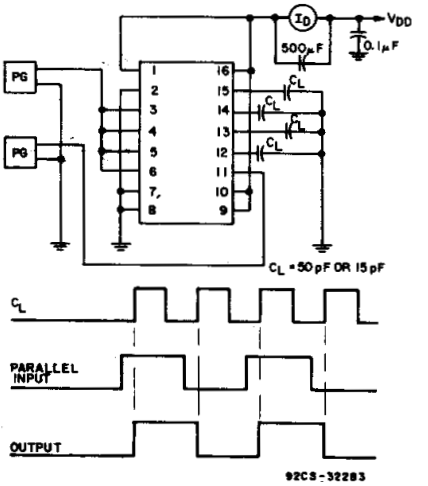


Fig. 10—Dynamic power dissipation test circuit.

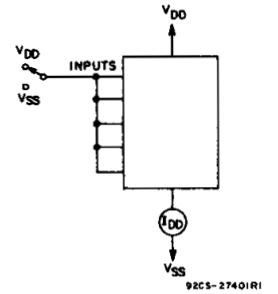


Fig. 11—Quiescent-device-current test circuit.

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C, Input t_r, t_f = 20 ns, C_L = 50 pF, R_L = 200 kΩ

CHARACTERISTIC	TEST CONDITIONS V_{DD} V	LIMITS Min.	Typ.	Max.	UNITS
Propagation Delay Time: Clock to Q t_{PHL}, t_{PLH}	5	—	220	440	ns
	10	—	100	200	
	15	—	70	140	
Output Transition Time t_{THL}, t_{TLH}	5	—	100	200	
	10	—	50	100	
	15	—	40	80	
Minimum Setup Time: t_S D0, D3, SR_{IN}, SL_{IN} to Clock	5	—	80	160	
	10	—	35	70	
	15	—	20	50	
SELECT 0, SELECT 1 to Clock	5	—	200	400	
	10	—	110	220	
	15	—	65	130	
Minimum Hold Time: t_H D0, D3, SR_{IN}, SL_{IN} to Clock	5	—	−65	0	
	10	—	−25	0	
	15	—	−15	0	
SELECT 0, SELECT 1 to Clock	5	—	−170	0	
	10	—	−95	0	
	15	—	−55	0	
Minimum Clock Pulse Width t_W	5	—	90	180	
	10	—	40	80	
	15	—	25	50	
Maximum Clock Input Frequency f_{CL}	5	3	6	—	MHz
	10	6	12	—	
	15	8	15	—	
Maximum Clock Rise or Fall Time t_rCL, t_fCL	5	—	—	1000	μs
	10	—	—	100	
	15	—	—	100	
Mininum Reset Pulse Width* t_{WR}	5	—	150	300	ns
	10	—	100	200	
	15	—	70	140	
Reset Propagation Delay t_{PRHL}	5	—	230	460	
	10	—	90	180	
	15	—	65	130	
Input Capacitance C_{IN}	Any Input	—	5	7.5	pF

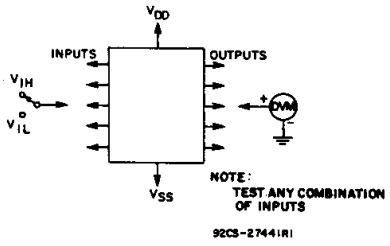


Fig. 12—Input-voltage test circuit.

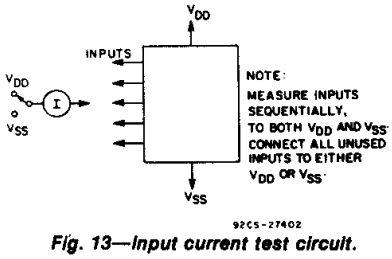
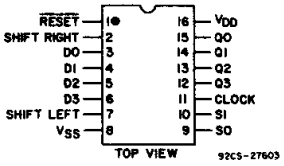


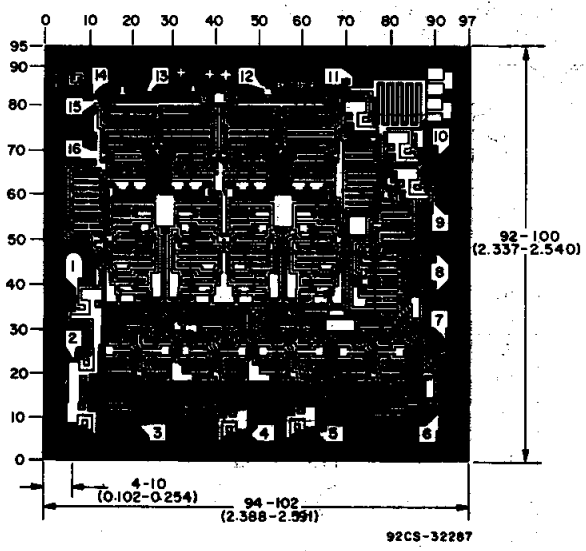
Fig. 13—Input current test circuit.

TERMINAL DIAGRAM

Top View



CD40194B



Dimensions and pad layout for CD40194BH

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CD40194BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD40194BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD40194BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD40194BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

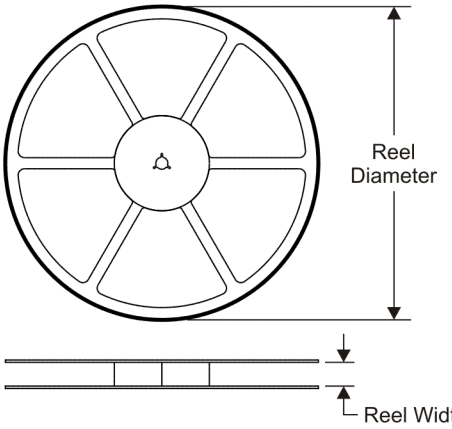
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

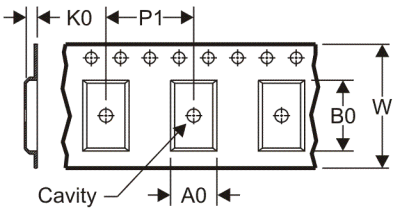
to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

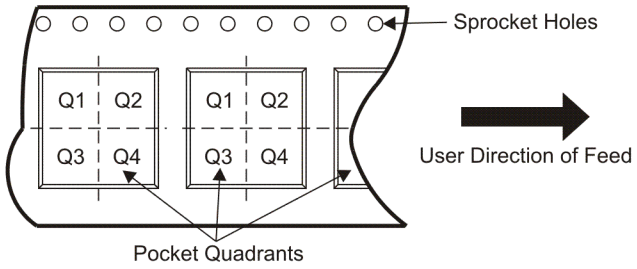


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

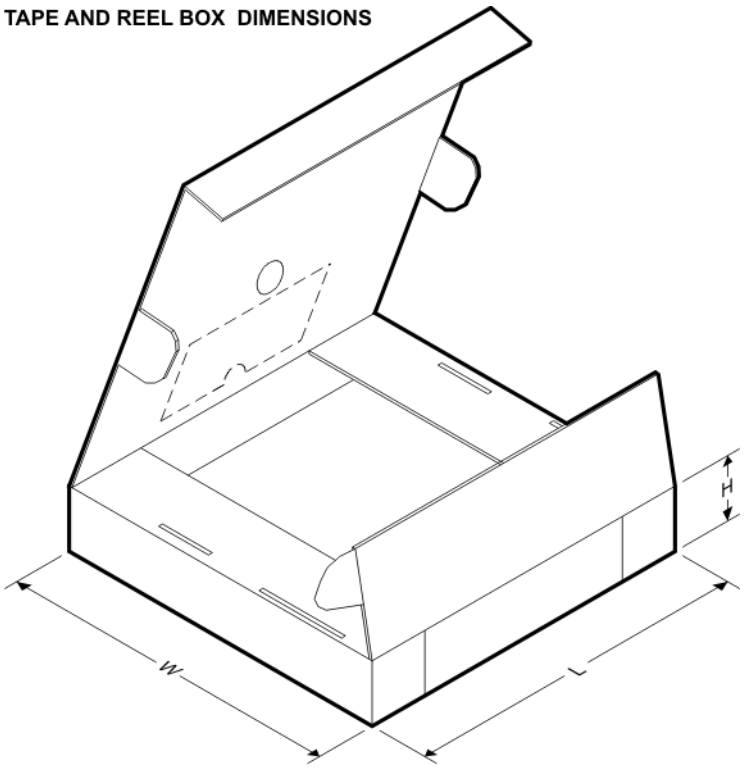
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD40194BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD40194BPWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



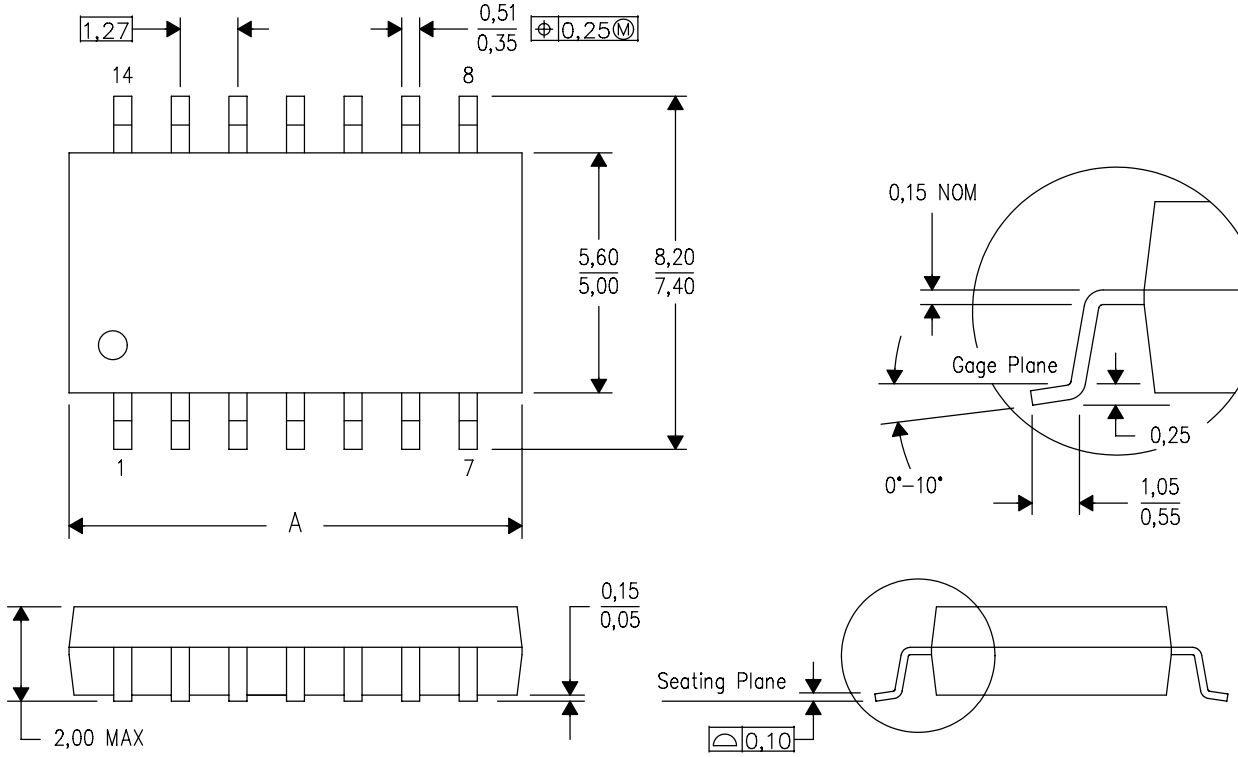
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD40194BNSR	SO	NS	16	2000	346.0	346.0	33.0
CD40194BPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



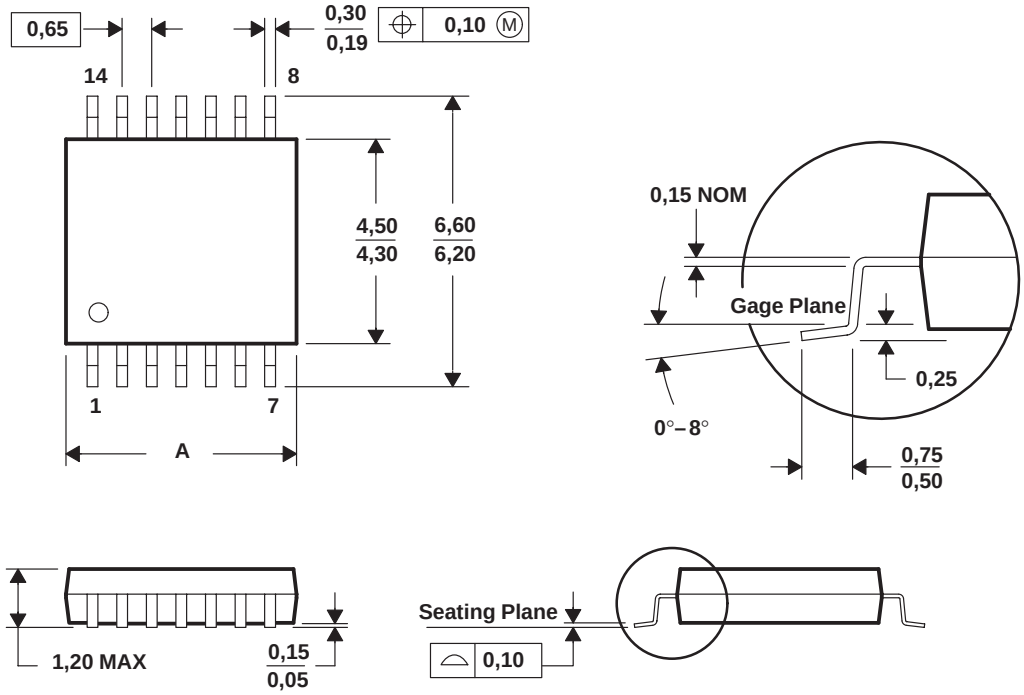
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

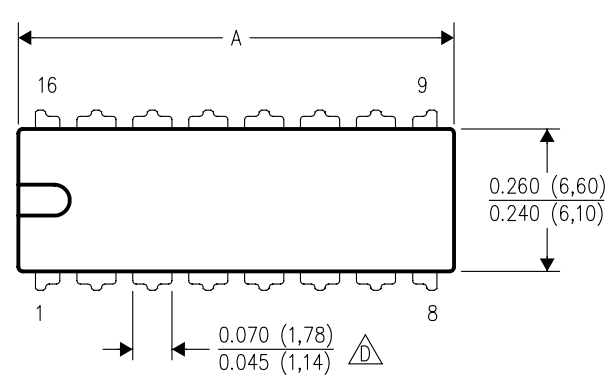
4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

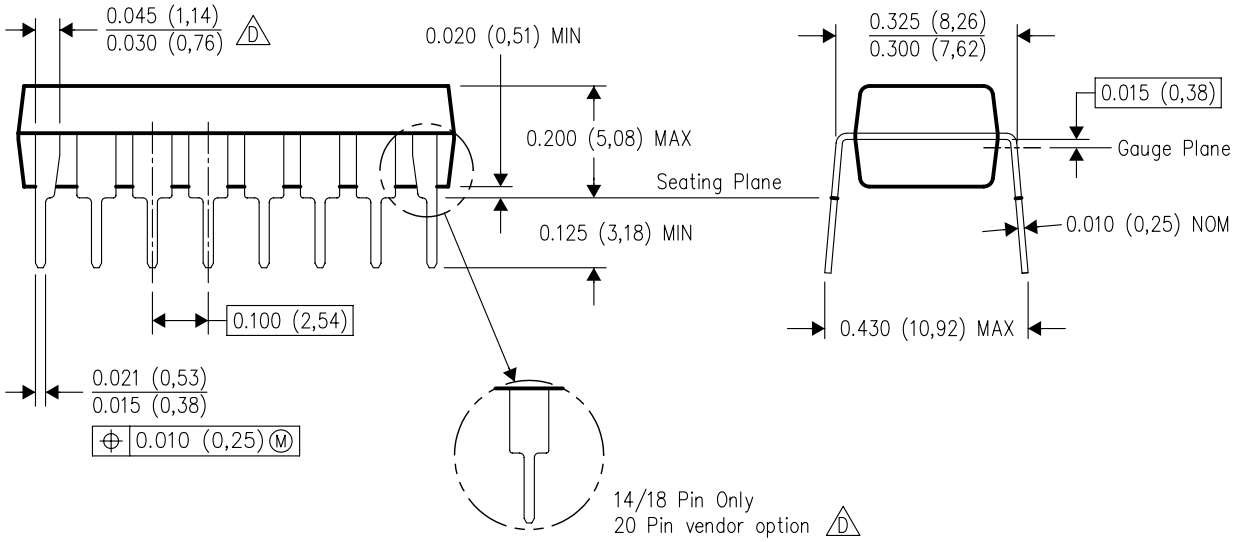
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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